Amendments to the Claims: This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A method of manufacturing a plasma display device having a panel in which a pair of substrates having transparency at least on a front side, the substrates being oppositely disposed so that discharge space and discharge cells are formed between the substrates, and a metallic holding plate that supports the panel via a thermal conductive material, the method comprising:

forming the thermal conductive material from a pull-to-remove type adhesive;

applying the adhesive to one of the panel and the holding plate;

bonding the panel to the holding plate together; and

curing the adhesive by application of pressure and heat[[,]].

wherein a groove in which a portion of the adhesive flows is formed at a periphery of the holding plate.

2. (Original) The method of manufacturing the plasma display device of Claim 1, wherein the adhesive is applied to one of the panel and the holding plate, the panel and the holding plate are bonded together, and then the adhesive is cured by simultaneous application of pressure and heat.

3. (Cancelled)

4. (Cancelled)

5. (Cancelled)

6. (Cancelled)

7. (Cancelled)

8. (Cancelled)

9. (Cancelled)

10. (Cancelled)

11. (Cancelled)

12. (Cancelled)

13. (Original) The method of manufacturing the plasma display device of Claim 1, wherein a driving circuit block containing a semiconductor device for feeding a display signal to the panel is mounted on a cooling plate on a back side of the holding plate, a portion of the thermal conductive material is exposed from the holding plate, and the driving circuit block-mounted cooling plate is bonded with the exposed portion of the thermal conductive material.

14. (Original) The method of manufacturing the plasma display device of Claim 1, wherein a driving circuit block containing a semiconductor device for feeding a display signal to the panel is mounted on a cooling plate on a back side of the holding plate, a portion of the thermal conductive material is extended to the driving circuit block-mounted cooling plate.

15. (Cancelled)

16. (Cancelled)